

L Number	Hits	Search Text	DB	Time stamp
1	12731	packag\$3 same (chip\$1 die\$1 dice\$1) and (multiple multi) adj5 (module\$1 layer\$2)	USPAT; US-PGPUB; EPO; JPO	2004/03/12 09:48
2	2397	(packag\$3 same (chip\$1 die\$1 dice\$1) and (multiple multi) adj5 (module\$1 layer\$2)) and (pcb\$2 circuit\$1 adj board\$1) near20 (si silicon semiconductor polysilicon)	USPAT; US-PGPUB; EPO; JPO	2004/03/12 10:02
3	278	((packag\$3 same (chip\$1 die\$1 dice\$1) and (multiple multi) adj5 (module\$1 layer\$2)) and (pcb\$2 circuit\$1 adj board\$1) near20 (si silicon semiconductor polysilicon)) and (pcb\$2 circuit\$1 adj board\$1) near7 (si silicon semiconductor polysilicon) and high adj frequency	USPAT; US-PGPUB; EPO; JPO	2004/03/12 09:53
4	113	((packag\$3 same (chip\$1 die\$1 dice\$1) and (multiple multi) adj5 (module\$1 layer\$2)) and (pcb\$2 circuit\$1 adj board\$1) near20 (si silicon semiconductor polysilicon)) and (pcb\$2 circuit\$1 adj board\$1) near7 (si silicon semiconductor polysilicon) and high adj frequency	USPAT; US-PGPUB; EPO; JPO	2004/03/12 10:02
5	113	((packag\$3 same (chip\$1 die\$1 dice\$1) and (multiple multi) adj5 (module\$1 layer\$2)) and (pcb\$2 circuit\$1 adj board\$1) near20 (si silicon semiconductor polysilicon)) and (pcb\$2 circuit\$1 adj board\$1) near7 (si silicon semiconductor polysilicon) and high adj frequency) and signal same power same ground	USPAT; US-PGPUB; EPO; JPO	2004/03/12 10:02